



AUTOMOTIVE & INDUSTRIAL

October 2023

DISCLAIMER

This document is provided by Soitec (the “Company”) for information purposes only.

The Company’s business operations and financial position are described in the Company’s 2022-2023 Universal Registration Document (which notably includes the 2022- 2023 Annual Financial Report) which was filed on June 14, 2023 with the French stock market authority (Autorité des Marchés Financiers, or AMF) under number D.23-0482. The French version of the 2022-2023 Universal Registration Document and its English courtesy translation for information purposes are available for consultation on the Company’s website (www.soitec.com), in the section Company - Investors - Financial Reports.

This document contains summary information and should be read in conjunction with the 2022-2023 Universal Registration Document.

This document contains certain forward-looking statements concerning Soitec. In some cases, you can identify these forward- looking statements by forward- looking words, such as “estimate”, “expect”, “anticipate”, “project”, “plan”, “intend”, “objective”, “believe”, “forecast”, “guidance”, “outlook”, “foresee”, “likely”, “may”, “should”, “goal”, “target”, “might”, “will”, “could”, “predict”, “continue”, “convinced” and “confident,” the negative or plural of these words and other comparable terminology. These forward-looking statements include, but are not limited to, predictions of the Company’s future prospects, activities, operations, direction, performance, results and strategy of Soitec and are based on analyses of earnings forecasts and estimates of amounts not yet determinable.

By their nature, forward-looking statements are subject to a variety of risks and uncertainties as they relate to future events and are dependent on circumstances that may or may not materialize in the future.

Forward-looking statements are not a guarantee of the Company’s future performance. The occurrence of any of the risks identified by the Company and described in Chapter 2.1 (Risk factors and controls mechanism) of the Company’s 2022-2023 Universal Registration Document may have an impact on these forward-looking statements.

The Company’s actual financial position, results and cash flows, as well as the trends in the sector in which the Company operates may differ materially from those contained in this document. Furthermore, even if the Company’s financial position, results, cash-flows and the developments in the sector in which the Company operates were to conform to the forward- looking

statements contained in this document, such elements cannot be construed as a reliable indication of the Company’s future results or developments.

Due to rounding, the sum of values presented in this presentation may differ from totals as reported. Such differences are not material.

The Company does not undertake any obligation to update or make any correction to any forward-looking statement in order to reflect an event or circumstance that may occur after the date of this document.

This document does not constitute or form part of an offer or a solicitation to purchase, subscribe for, or sell the Company’s securities in any country whatsoever. This document, or any part thereof, shall not form the basis of, or be relied upon in connection with, any contract, commitment or investment decision. Notably, this document does not constitute an offer

or solicitation to purchase, subscribe for or to sell securities in the United States. Securities may not be offered or sold in the United States absent registration or an exemption from the registration under the U.S. Securities Act of 1933, as amended (the “Securities Act”). The Company’s shares have not been and will not be registered under the Securities Act.

Neither the Company nor any other person intends to conduct a public offering of the Company’s securities in the United States.

AGENDA

#01
SOITEC
AT A GLANCE

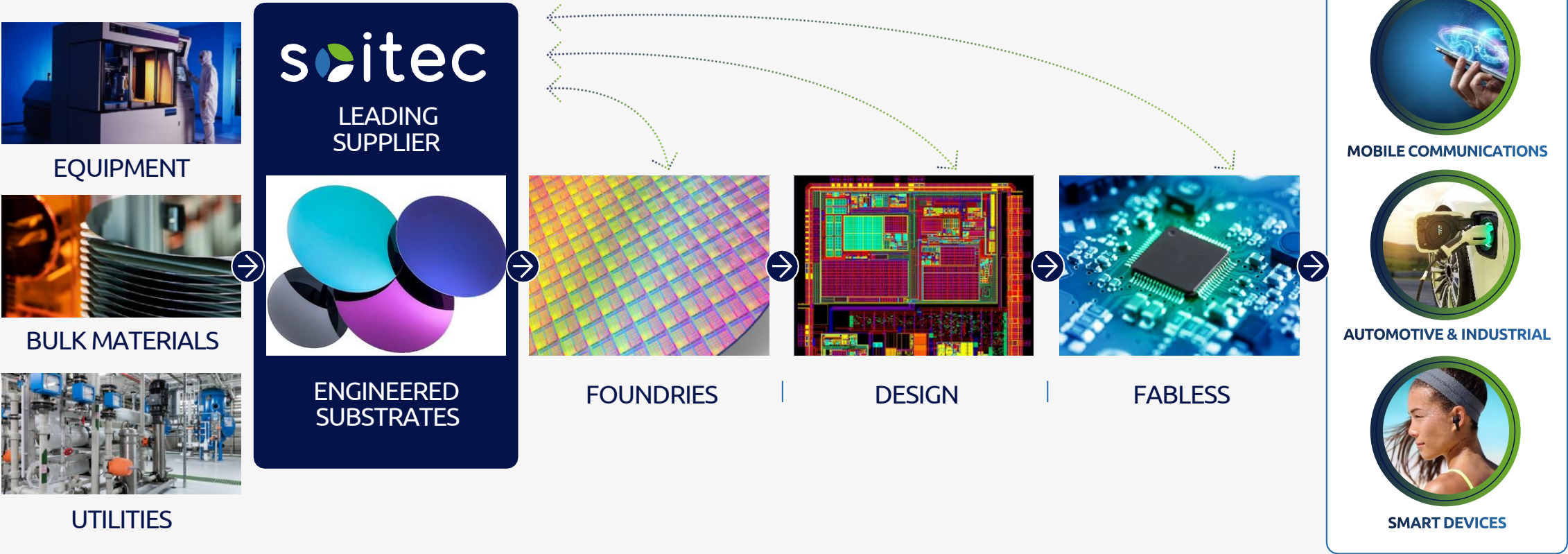
#02
AUTOMOTIVE
& INDUSTRIAL

#03
SMARTSiC™
ADOPTION

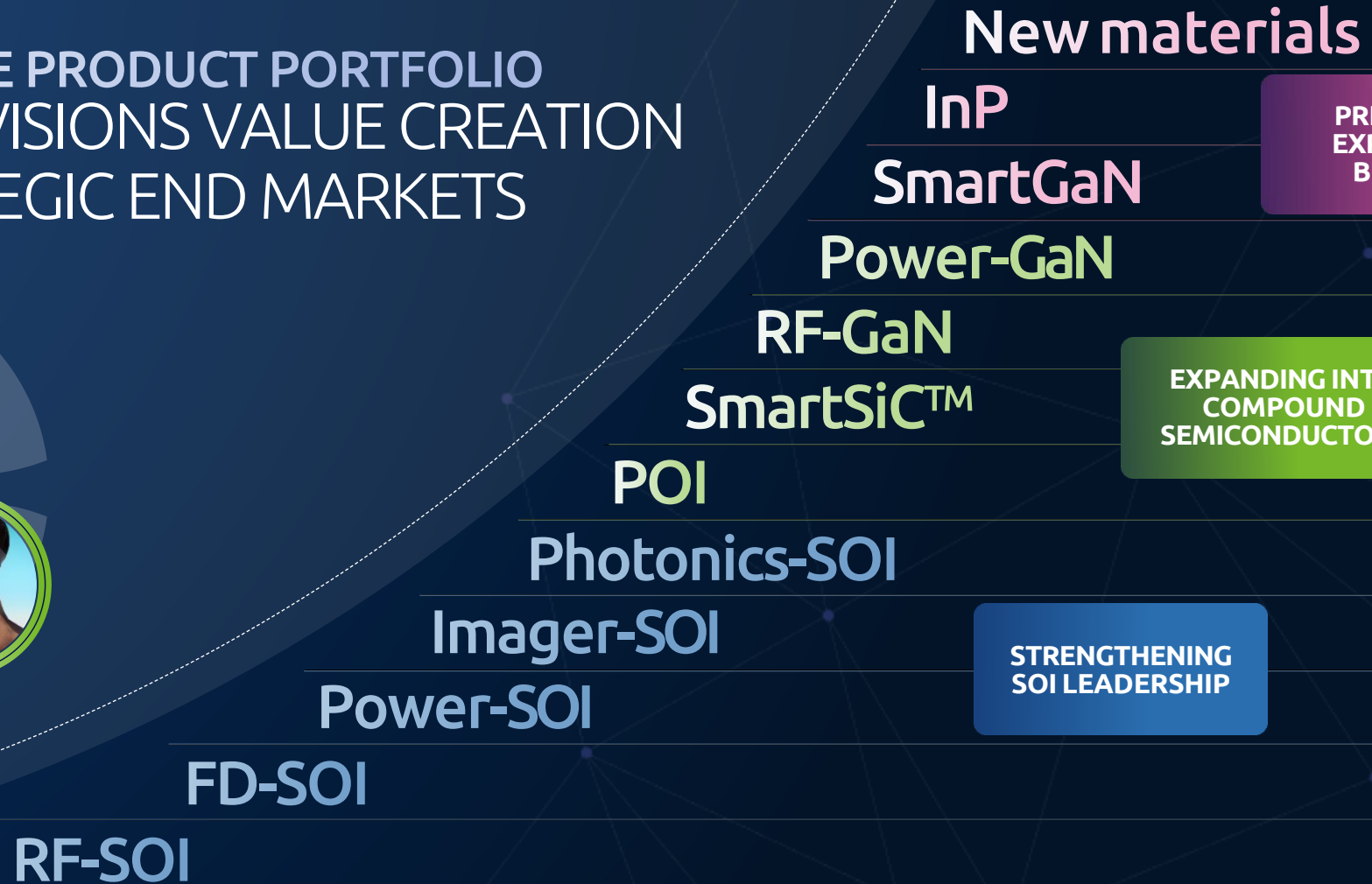
SOITEC AT A GLANCE

SOITEC HAS BUILT A UNIQUE POSITION IN THE VALUE CHAIN

BUILDING CUSTOMER INTIMACY TO MAKE OUR PRODUCTS
A STANDARD AND BECOME A REFERENCE

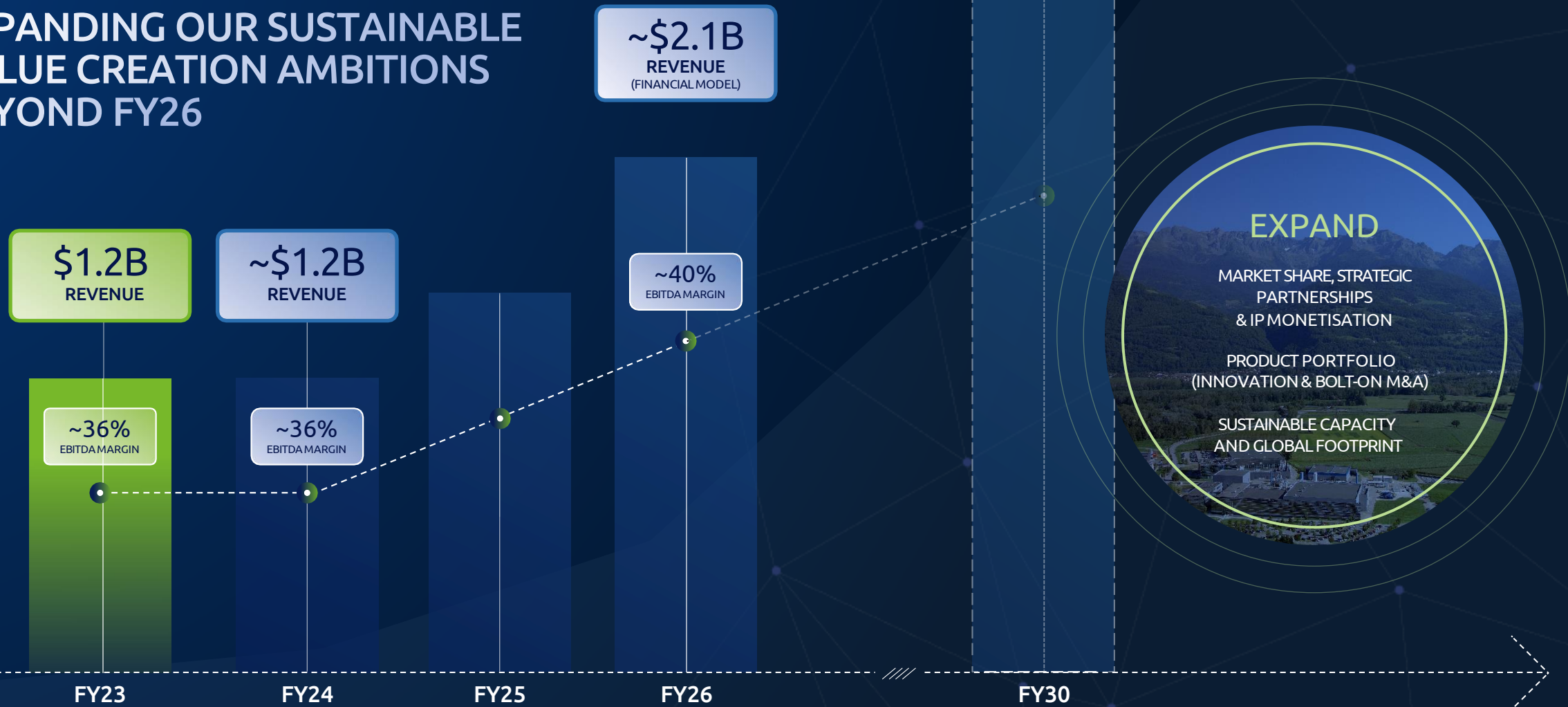


BUILDING A DIVERSE PRODUCT PORTFOLIO TO FUEL OUR DIVISIONS VALUE CREATION ACROSS 3 STRATEGIC END MARKETS



+ LICENSING / PATENT MONETIZATION

EXPANDING OUR SUSTAINABLE VALUE CREATION AMBITIONS BEYOND FY26



EBITDA represents operating income (EBIT) before depreciation, amortization, impairment of non-current assets, non-cash items relating to share-based payments, provisions for impairment of current assets and for contingencies and expenses, and disposal gains and losses. EBITDA is not a financial indicator defined by IFRS and may not be comparable to EBITDA as reported by other groups. It represents additional information and should not be considered as a substitute for operating income or net cash generated by operating activities

RAMPING GLOBAL INDUSTRIAL FOOTPRINT TO ADDRESS GROWING DEMAND IN SOI AND COMPOUND ENGINEERED SUBSTRATES



SOITEC BERNIN 1 - SOI 200
FRANCE

RF-SOI

Power-SOI

Photonics-SOI



SOITEC BERNIN 2 - SOI 300
FRANCE

RF-SOI

FD-SOI

Photonics-SOI

Imager-SOI



SOITEC BERNIN 3 - POI
FRANCE

POI



SOITEC BERNIN 4 - SmartSiC™
FRANCE

SmartSiC™

300mm Refresh

Extension under
construction



SOITEC PASIR RIS 1 - SOI 300
SINGAPORE

RF-SOI

FD-SOI

Photonics-SOI

Refresh



SOITEC PASIR RIS 1A - SOI 300
SINGAPORE

RF-SOI

FD-SOI

Photonics-SOI

Refresh

Extension under
construction



SIMGUI PARTNERSHIP - SOI 200
CHINA

RF-SOI

Power-SOI



SOITEC BELGIUM - GaN
BELGIUM

GaN

SOI Wafers
Compound Wafers

~ **1.45 mwpy**

200mm SOI capacity reaching limit

- **B1:** full at 1M
- **Simgui:** up to 450K

↗ **Up to 2.75 mwpy**

300mm SOI capacity target

- **B2:** 750K by end of FY25
- **PR1:** 1M by end of FY25
- **PR1A:** up to 1M in line with customer demand

↗ **Up to 700 kwpy**

Ramping capacity for POI in **B3**

↗ **Up to 500 kwpy**

Ramping capacity for SmartSiC™ in **B4**
First production expected Q3 FY24

↗ **Up to 60 kwpy**

For Epi capacity in **Hasselt**

A DIVERSE AND STREAMLINED MANAGEMENT TEAM

FOCUSED ON VALUE CREATION
EXPANSION, SPEED OF EXECUTION,
AND DELIVERY OF OUR AMBITIOUS
STRATEGIC PLAN



(1) As of October 2023

AUTOMOTIVE & INDUSTRIAL



GROWTH DRIVERS AUTOMOTIVE & INDUSTRIAL

AUTOMOTIVE – In vehicle

Car increasingly becoming a connected hub

- In-vehicle Networking
- In-vehicle Sensors & Actuators
- Power Management IC (PMIC)
- System Basis Chip (SBC)
- Multimedia application processor
- ClassD audio amplifier

AUTOMOTIVE – Edge computing

Improving automation features to improve functional safety

- Front, Rear, Edge & imaging radars
- MCU/ MPU
- Vision / Data Fusion Processor
- LiDARs
- Zonal / Edge Computing
- Airbag / Braking system

AUTOMOTIVE – Powertrain

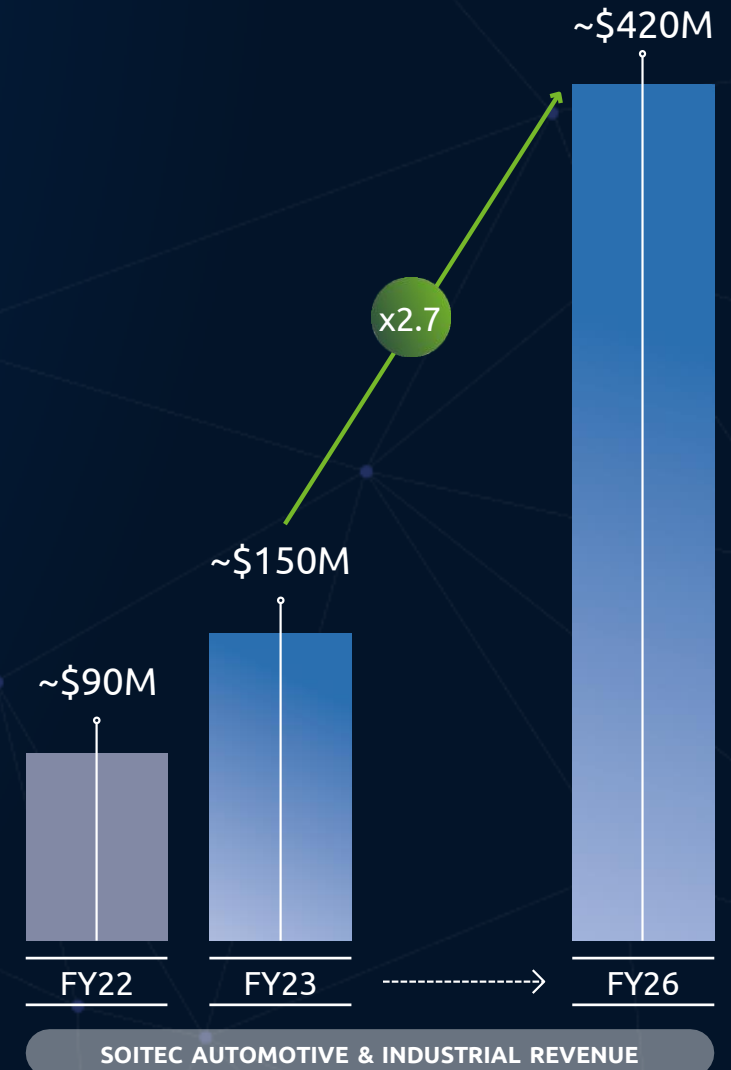
Accelerating Electric Vehicle adoption

- Powertrain / Traction inverter
- On-Board Charger
- Battery Management System
- DC-DC converter

INDUSTRIAL – Industry 4.0

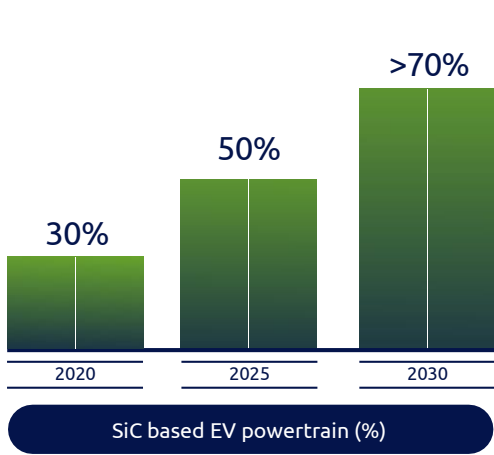
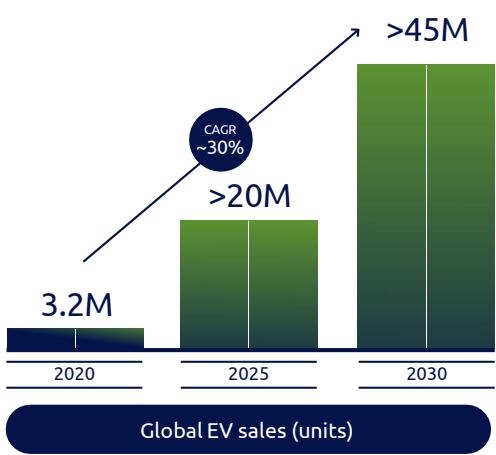
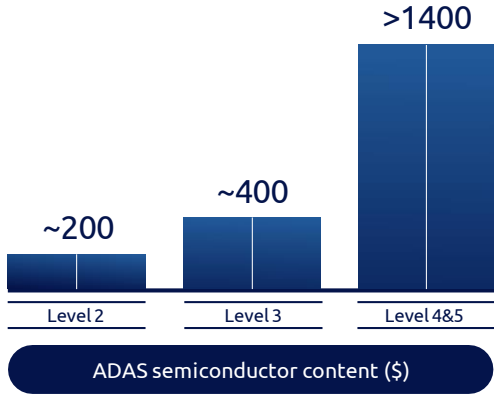
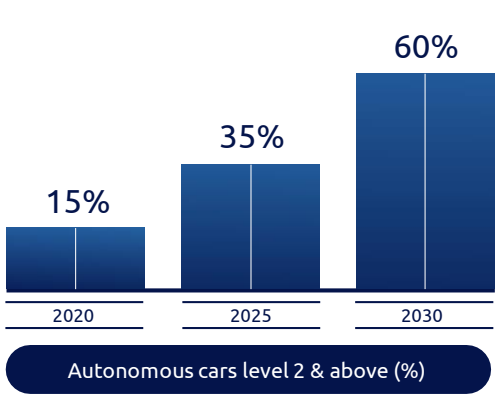
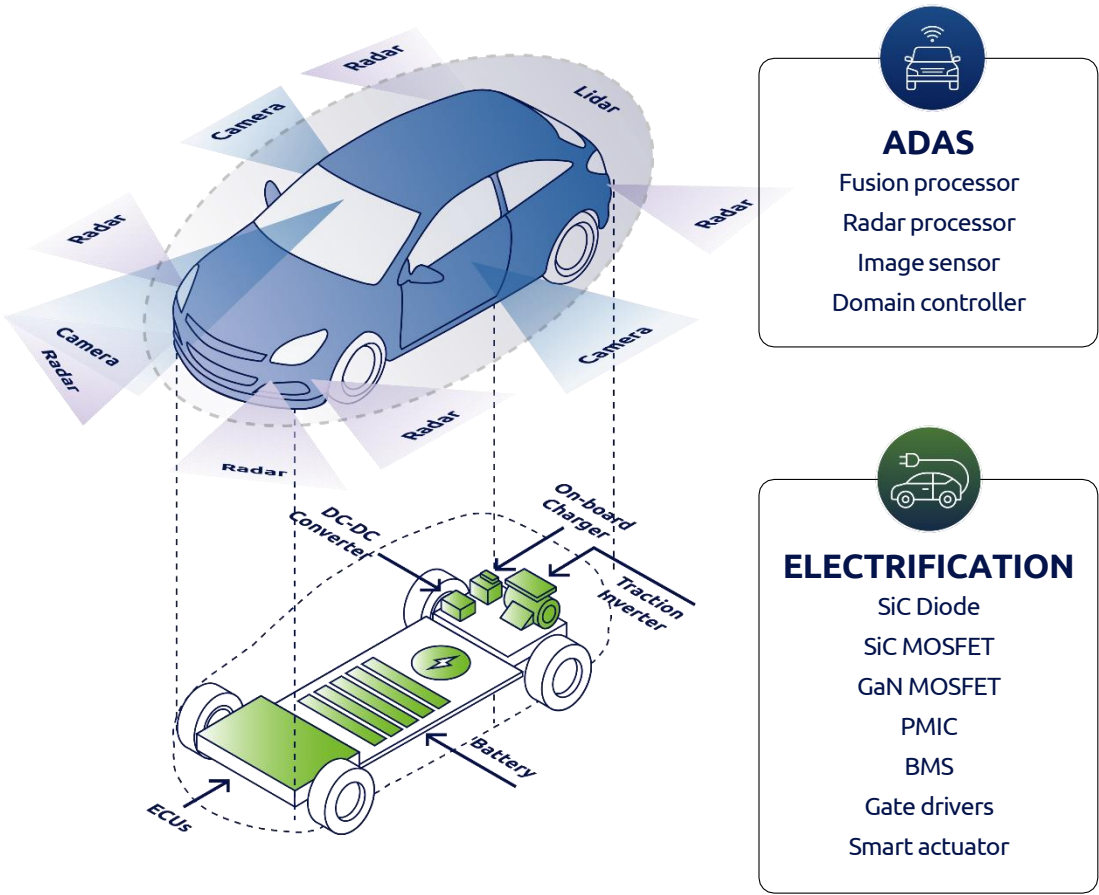
Enabling factories of the future with more safety, automation and efficiency

- Solar field DC/AC stations
- Motor drive & gate driver
- Power converter
- PMICs & SBCs
- Low CO₂ footprint power devices



AUTOMOTIVE MEGATRENDS

DRIVE INNOVATION FROM SYSTEMS TO SUBSTRATES



Source: Soitec estimates, Infineon, NXP, IHS, The International Council on Clean Transportation (ICCT) 2020



POWERTRAIN – A CRITICAL COMPONENT OF THE EV MARKET

SiC ADDS VALUE AT SYSTEM LEVEL AND ENABLES COST REDUCTION

POWERTRAIN COST: ~\$10,000

ELECTRIC MOTOR

- Electric motors
- e-transmission

~\$1,100 ↘

BATTERY PACK & MODULES

- Battery pack
- Modules and cells
- BMS

~\$8,000 ↘

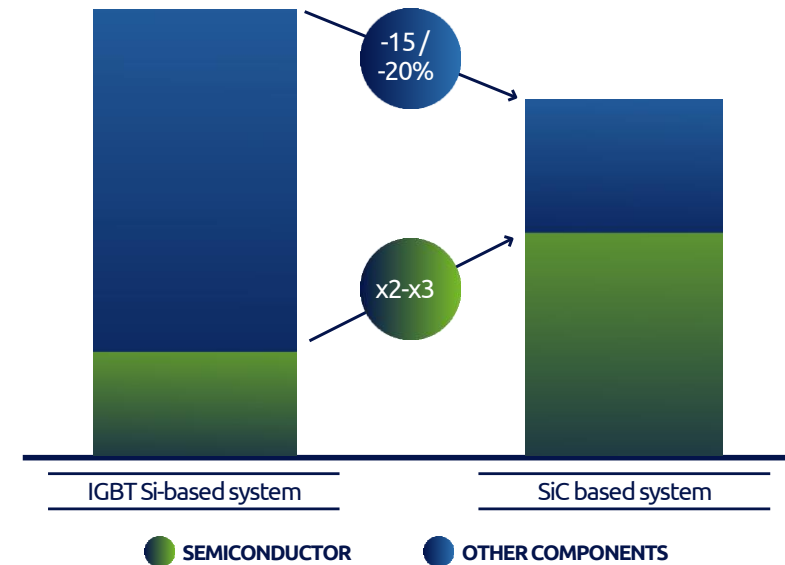
POWER ELECTRONICS

- E-drive / inverter (DC/AC)
- DC/DC Converter
- On-board charger (AC/DC)

~\$1,500 →

STANDARDISATION
OF 800V IN BATTERY
ACCELERATES SiC
ADOPTION

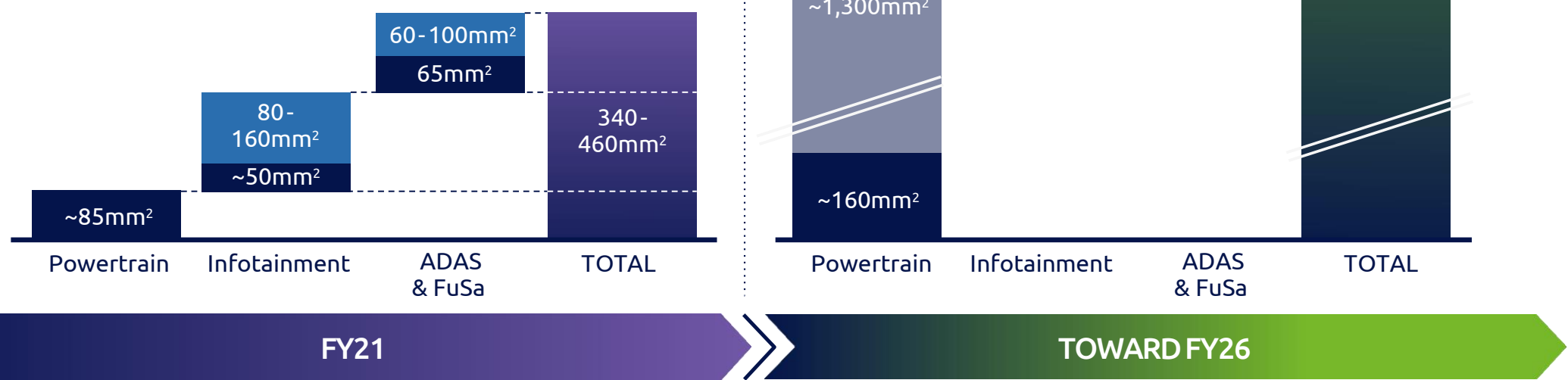
TOTAL SYSTEM COST – 15-20% REDUCTION



Shorter charge time 800V	~50% FASTER
Increased battery range	~5-10% LONGER
Reduced system / battery cost	~\$500-\$1,000

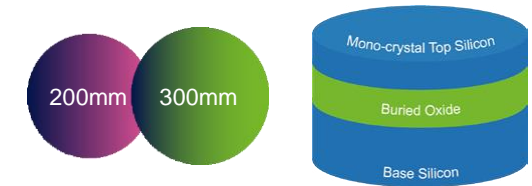
AUTOMOTIVE CONTENT OPPORTUNITY IN THE NEXT THREE YEARS IN mm²

- Auto Power-SOI
- Auto FD-SOI
- Auto SmartSiC™
- Auto Power-GaN



AUTOMOTIVE & INDUSTRIAL PRODUCT PORTFOLIO

AUTO POWER-SOI



AUTO POWER-SOI FOR IVN, PMIC, SBC, BMS & GATE DRIVERS



AUTO POWER-SOI ENABLES SUPERIOR PERFORMANCE OVER BULK SILICON

EFFICIENT

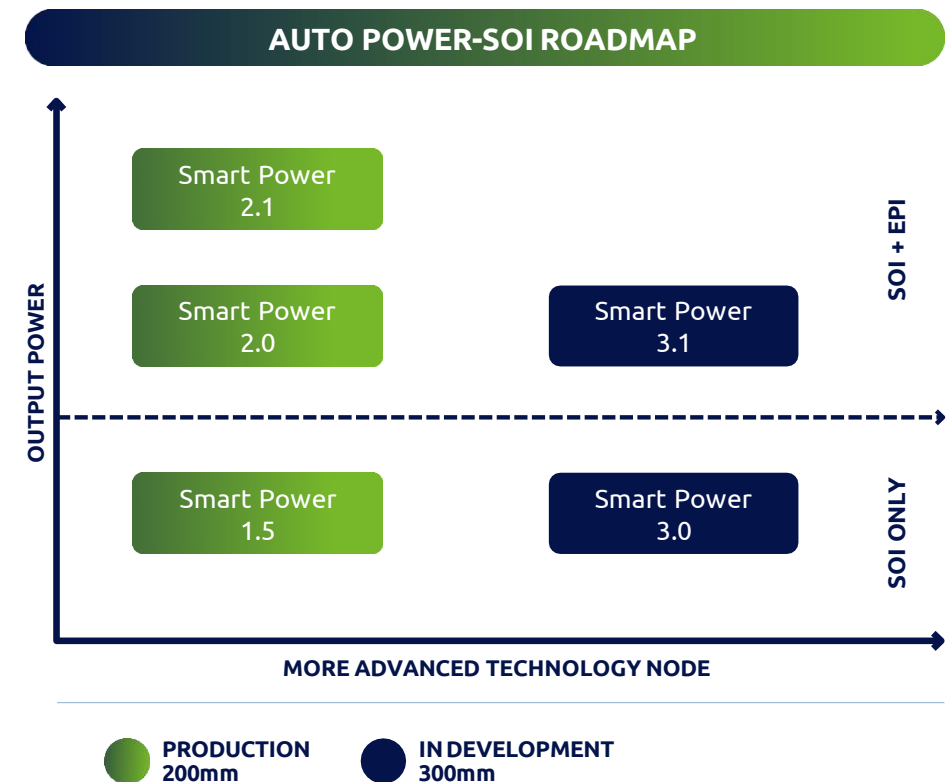
>10%
SYSTEM COST REDUCTION
& EFFICIENCY
IMPROVEMENT

SAFER

HIGHER
ROBUSTNESS,
NOISE IMMUNITY
AND OPERATING
TEMPERATURE

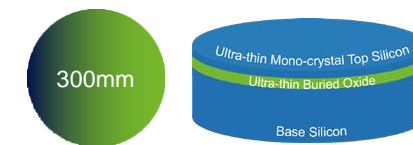
BETTER

> 40x
SMALLER
ISOLATION AREA
> 50%
DIE SIZE REDUCTION



AUTOMOTIVE & INDUSTRIAL PRODUCT PORTFOLIO

AUTO FD-SOI



AUTO FD-SOI EMPOWERS THE FUTURE OF AUTOMOTIVE AND INDUSTRIAL SMART DEVICES



ADAS



Radars



Industrial Automation

AUTO FD-SOI ENABLES SUPERIOR PERFORMANCE OVER BULK SILICON AND FINFET

SAVING POWER

~30%

GREENHOUSE GASES
EMISSION REDUCTION

SAVING LIVES

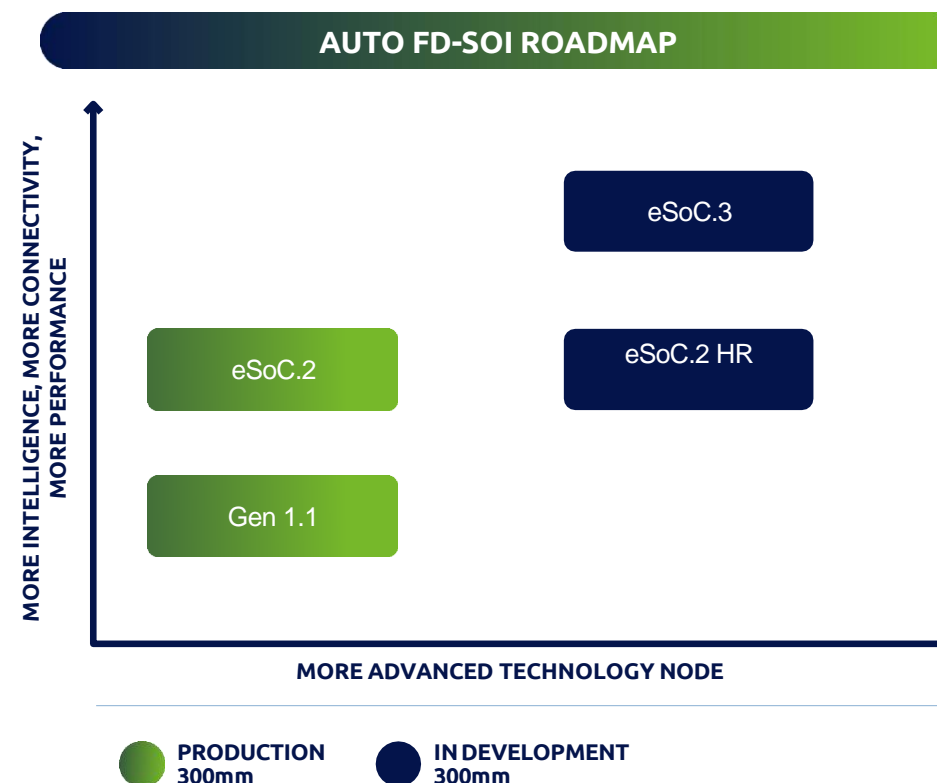
~50%

HIGHER DETECTION
RANGE IN RADARS

SAVING COST

~50%

DIE SIZE
REDUCTION



AUTOMOTIVE & INDUSTRIAL PRODUCT PORTFOLIO

AUTO SMARTSiC™



AUTO SmartSiC™, A DISRUPTIVE SOLUTION FOR LARGER SiC ADOPTION



Powertrain



Charging infrastructure



Renewable energies

AUTO SMARTSiC™, A NEW PARADIGM FOR DEVICE PERFORMANCE AND PRODUCTIVITY

GREENER

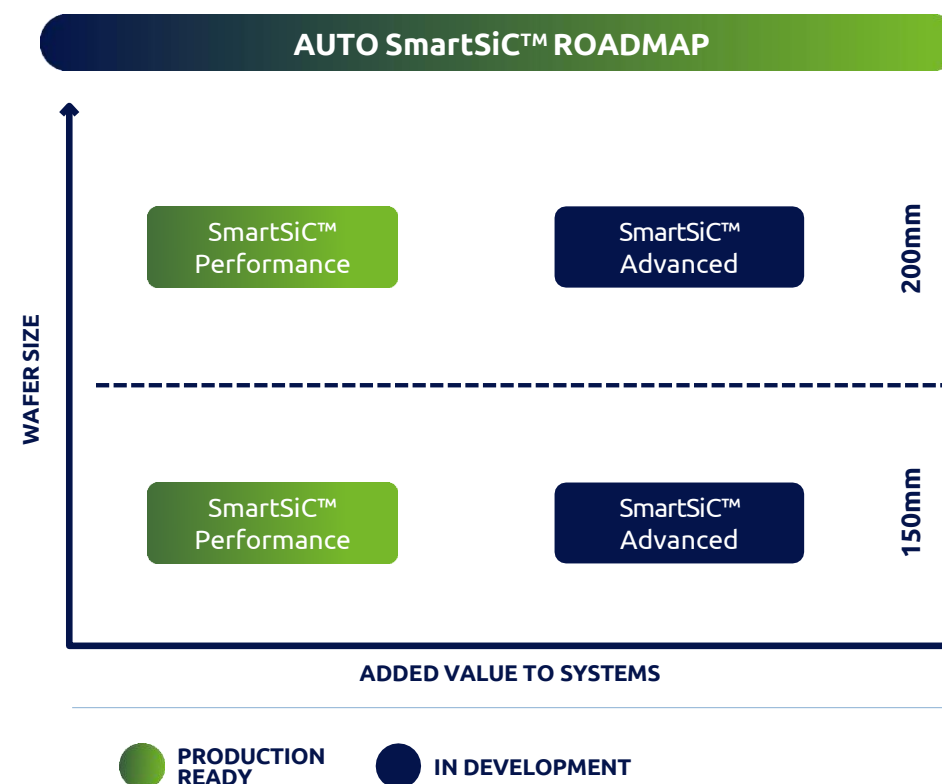
~70%
LOWER CO₂ FOOTPRINT
THAN STANDARD SiC
WAFERS

FASTER

2 YEARS
ACCELERATION OF MASS
DEPLOYMENT OF 200MM
SiC WAFERS

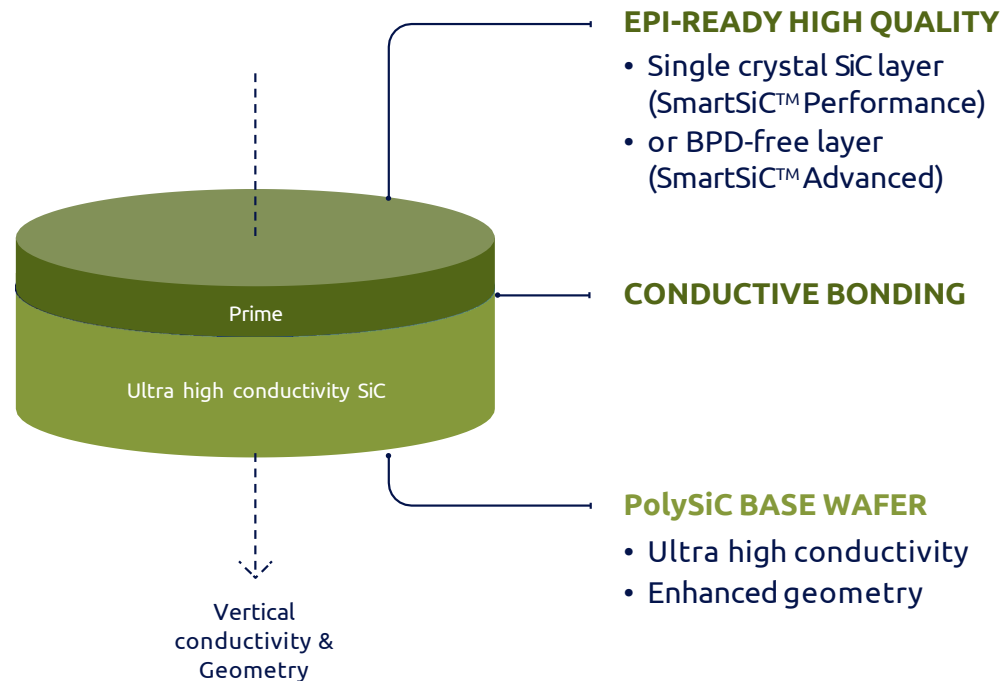
BETTER

UP TO 20%
HIGHER POWER DENSITY,
ENABLING MORE
COMPACT, LIGHTER AND
LESS COSTLY SYSTEMS



SMARTSiC™ ADOPTION

UNRIVALED VALUE PROPOSITION TO ENABLE EV ADOPTION



UNPARALLELED VALUE PROPOSITION

- **40,000 Tons of CO reduction** for each 1 million wafers vs SiC
- 200mm scalability to **accelerate SiC adoption** by 2 years through 10x re-usability
- Enabling new generations of SiC devices thanks to an **improvement of $R_{DS(on)}$ of up to 20%**
- **Reducing CAPEX & OPEX** for device manufacturers

>10x

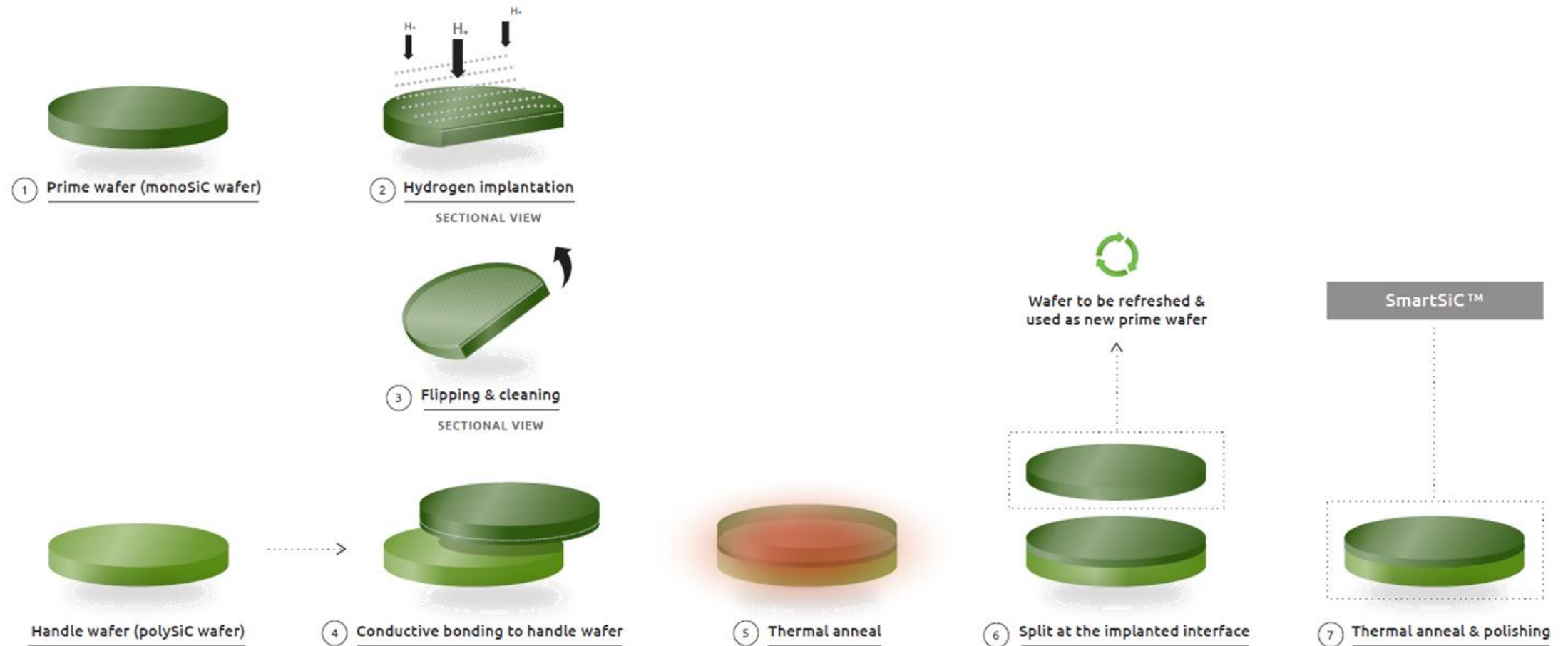
MONO-SiC WAFER
RE-USABILITY

~8x

POLY-SiC WAFER BETTER
CONDUCTIVITY

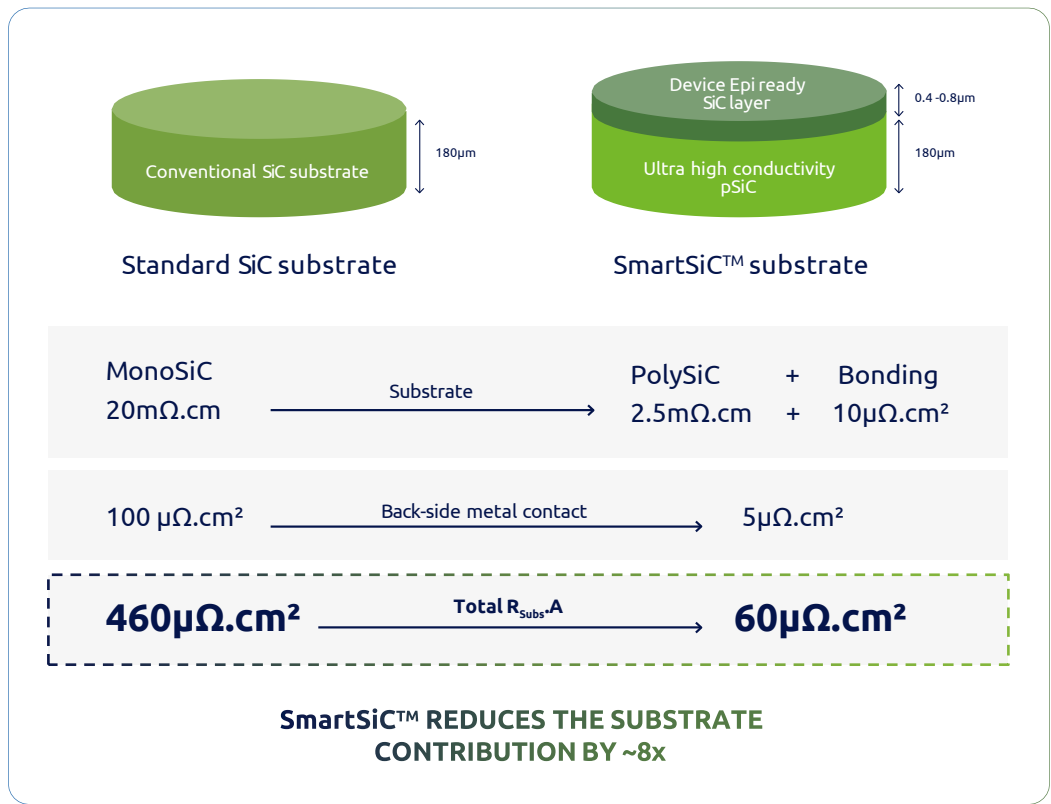
SMART CUT™ PROCESS ADAPTED TO SiC

LEVERAGING HIGH VOLUME MANUFACTURING EXPERIENCE: >2M WAFERS PER YEAR



SMARTSiC™ ENGINEERED SUBSTRATE DRIVING SIGNIFICANT PERFORMANCE GAIN AT DEVICE LEVEL

Lower R_{DSon} A



SmartSiC™ gains the equivalent to one-generation device improvements

MOSFET 1200V		A	B	C	D
Generation (release year)		3 (2022)	3 (2021)	2 (2022)	4 (2022)
MOSFET design		Planar	Planar	Trench	Trench
Back-grinding Thickness (in μm)		180	180	110	150
SmartSiC™	Gain (*) vs SiC	14.9%	14.9%	11.2%	14%

ADDITIONAL GAINS OF SMARTSiC™ ON BETTER FLATNESS
AND EASIER BACK-GRINDING PROCESS
+
GAINS ON CAPEX AVOIDANCE

* Soitec estimates based on publicly available information

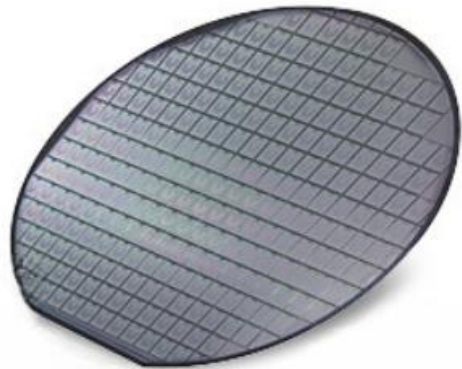
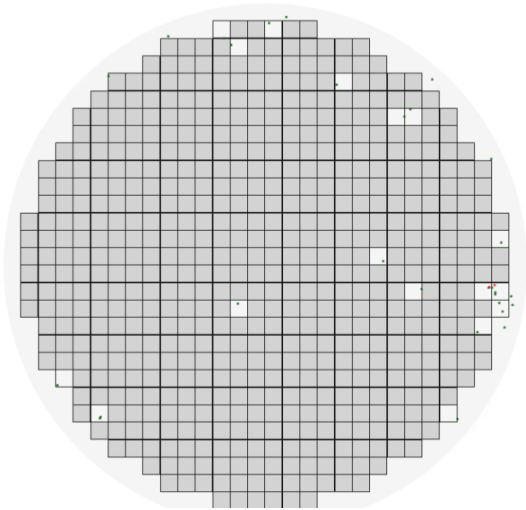


SMARTSiC™ ENABLES UP TO +25% DIE / WAFER IMPROVEMENTS

DIE SHRINK AND BETTER EFFICIENCY GENERATE MORE DIES PER WAFER

Constant R _{ON} redesign MOSFET 1200V			
200mm wafer	Single Crystal SiC	SmartSiC™	Gain
Initial die size	25mm²	21.3mm²	+15%
Gross dies / Wafer	1,108*	1,313*	+18%*
Die process yield	70% by 2024	74% by 2024	+4% by 2024
Good dies / Wafer	776 by 2024	969 by 2024	+25% by 2024

*Edge Exclusion : 3mm + Scribe line 80µm



Source: Littelfuse

SMARTSiC™

200mm DISRUPTIVE ACCELERATION FACTOR

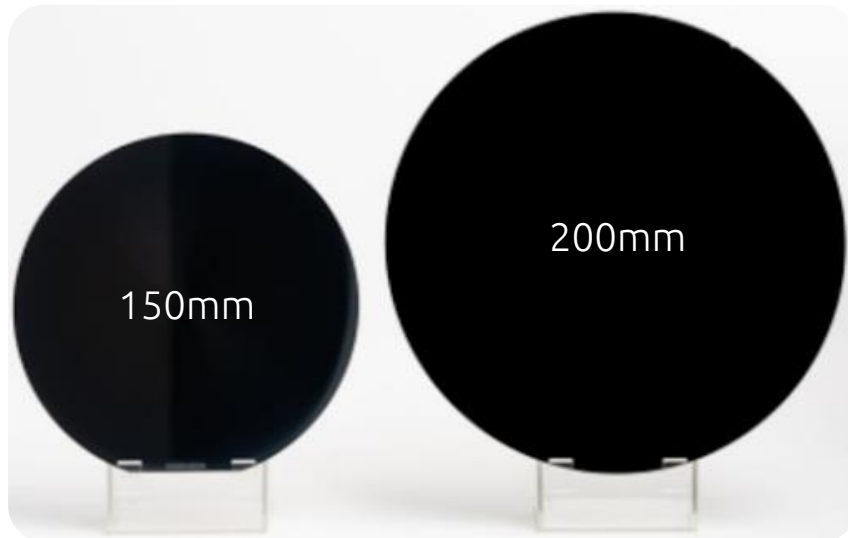
SMARTSiC™ ENABLES DEVICE MULTIPLICATION

~20%

Lower Die size
SmartSiC™ enabling
more products per wafer

x1.78

Higher surface area
200mm allowing
device multiplication



200mm SMARTSiC™ FURTHER DIFFERENTIATION

200mm further adds to 150mm SmartSiC™
performance improvements



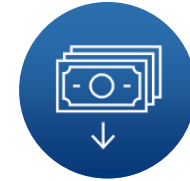
Higher **yield** through
repeatability



Better **efficiency** of
Smart Cut™ bonding



Fast **scalability**
in 200mm



Lower **cost of**
ownership



STMICROELECTRONICS AND SOITEC COOPERATE ON SIC SUBSTRATE MANUFACTURING TECHNOLOGY

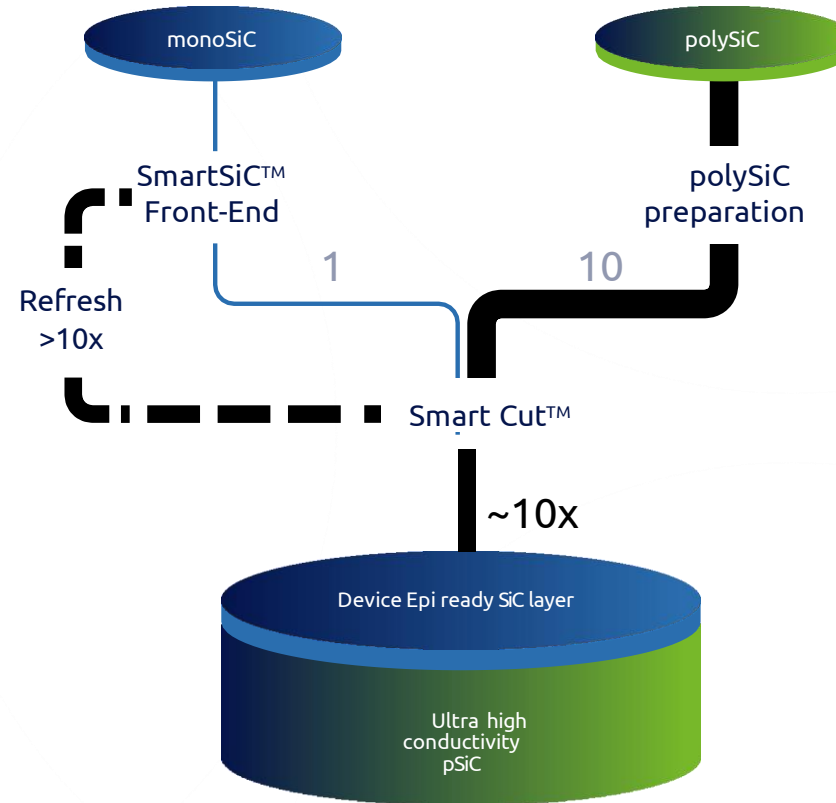
- Partnering with a pioneer and leader of SiC Power Devices in the Automotive Industry
- Main goal: Qualifying 200mm product
- SmartSiC™ is a game-changer for automotive chip manufacturing

SUSTAINABLE AND AGILE SUPPLY CHAIN

monoSiC

FLEXIBLE SUPPLY MODEL

- Qualification strategy customized to customer requirements
- 3 suppliers already engaged:
 - vertically integrated
 - independent sources
- Suppliers located in different regions



**CO₂ EMISSION SAVING OF MORE
THAN 70% COMPARED TO
CONVENTIONAL SiC**

polySiC

ECOSYSTEM DRIVEN BY SOITEC

- Suppliers targeted across different regions
 - 1 supplier under LTA
 - 2 suppliers engagement on track with roadmap
 - Others under evaluation
- Strong collaboration with suppliers to design the most efficient polySiC wafers
- High degree of agility between 150mm and 200mm wafers

BERNIN 4

NEW CLEANROOM FOR SMARTSiC™ 500kwp 150/200mm CAPACITY

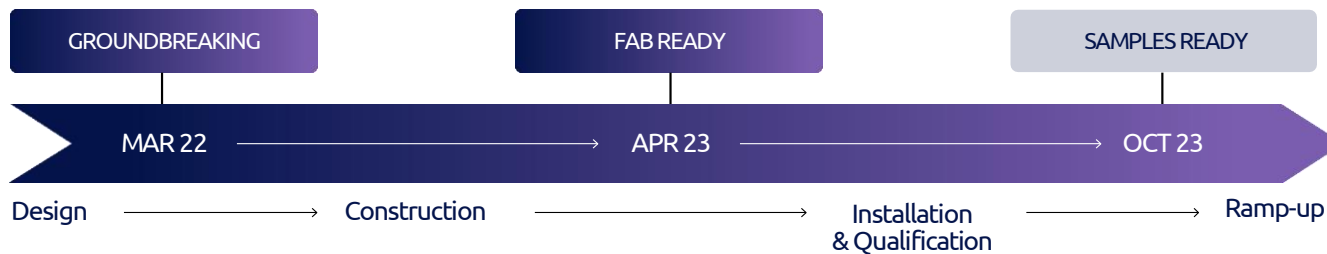


BERNIN 4

TRIGGER SMARTSiC™ CAPACITY

High flexibility 150-200mm Designed with efficient principles

- 2,000m² agile new cleanroom able to produce SmartSiC™ 150/200mm
- 300mm Refresh located in the same building to enable fixed cost absorption as early as CY24
- Facilities redundancy, industrial synergies (utilities, warehouse, know-how...)
- Fully connected with former cleanroom and new logistics platform



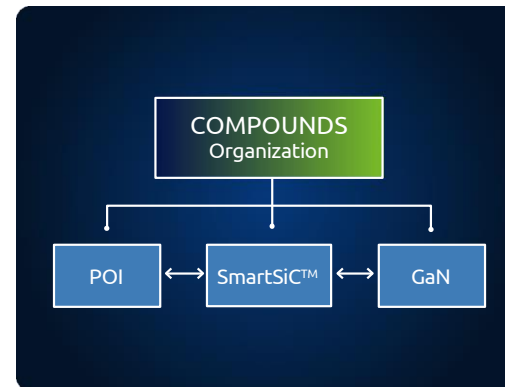
RAMPING A SCALABLE AND AGILE MODEL



JUST-IN-TIME SUPPLY CHAIN

ADAPTING SUPPLY TO CUSTOMER DEMAND

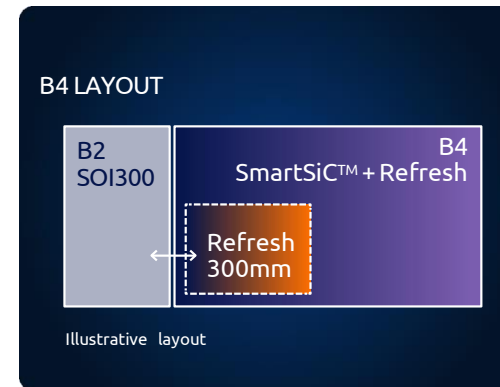
- Piloting equipment installation
- Driving raw material supply implementation



OPTIMIZE COMPOUND ORGANIZATION

LEVERAGING ASSET SYNERGIES

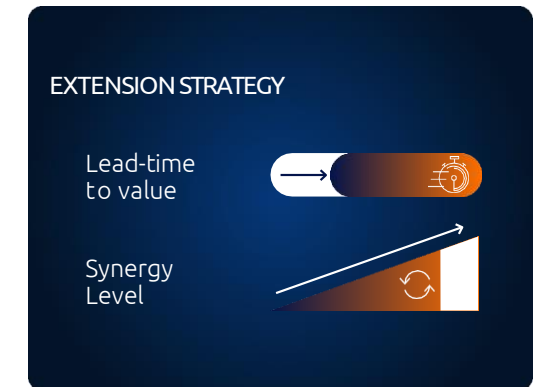
- >50% for POI / SmartSiC™ Tools
- ~90% of tools are bridge 150 / 200mm (both POI and SmartSiC™)
- Global Compounds team



DEPLOYING AGILE FABS

ENABLING FIXED COST ABSORPTION

- SmartSiC™ / 300mm SOI refresh
- Ramp-up designed to absorb fixed costs early stage through refresh / epi



FAB EXTENSIONS

DELIVERING SYNERGIES & ACCELERATED QUALIFICATION

- Synergies / Leveraging existing footprint
- Faster qualification

SMARTSiC™ ROADMAP

Recent Highlights

✓

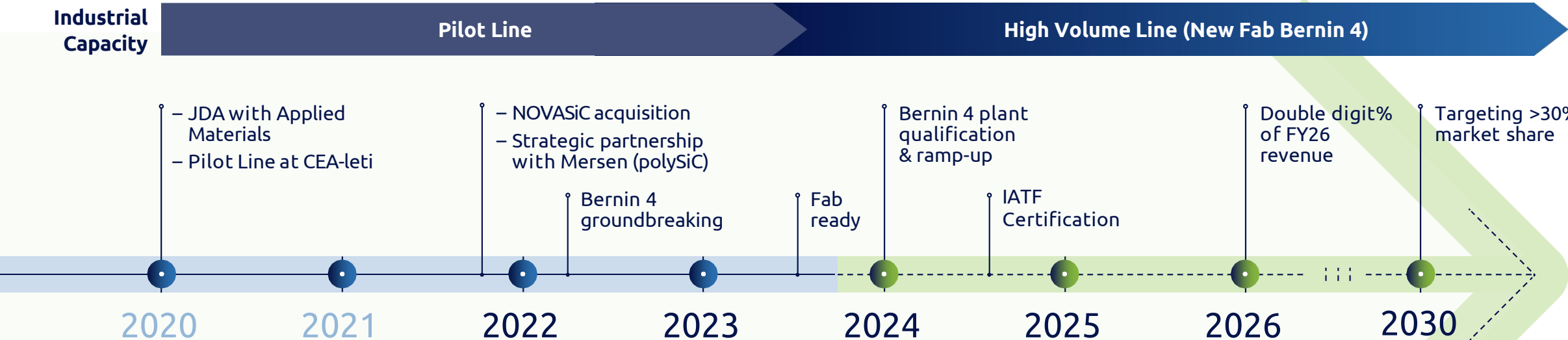
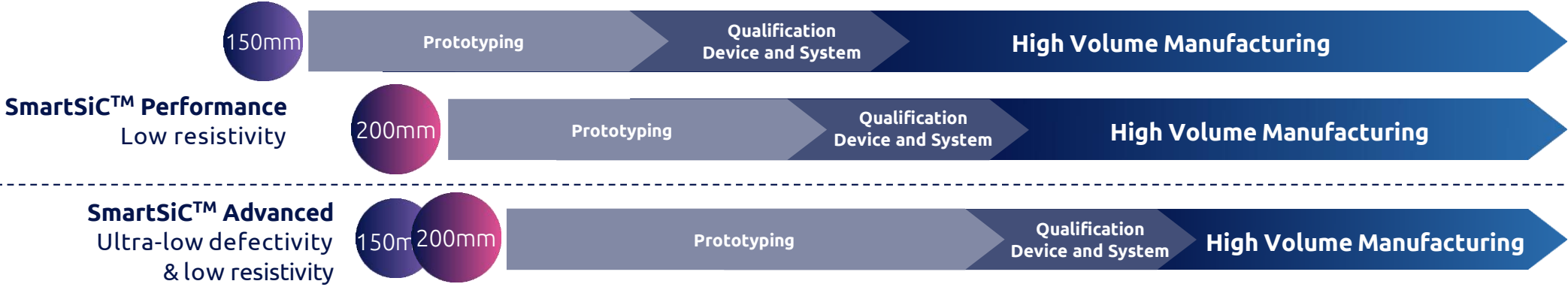
>1,000 prototypes delivered

✓

30 players engaged across 3 continents

✓

1 qualification ongoing with STMicroelectronics



AUTOMOTIVE & INDUSTRIAL KEY MESSAGES

AUTOMOTIVE & INDUSTRIAL DIVISION EXPECTED TO TRIPLE ITS REVENUE BY FY26

- We leverage 2 main trends, Digitalization & Electrification of the car
- The automotive semiconductor content opportunity is expected to x4 between FY21 and FY26
- SmartSiC™ expected to generate around 50% of the division revenue by FY26

A DYNAMIC AND ATTRACTIVE PRODUCT PORTFOLIO

- Power-SOI, a critical product to enable greater performance and support an increasing number of functional safety features
- FD-SOI is now a reality in the automotive industry, addressing the blossoming market of radars / LiDARs, the transition to Zonal Architectures and enabling AI for mobility

SMARTSiC™, AN INDUSTRY GAME CHANGER

- Silicon Carbide is positioning itself as the new standard for EV powertrain and an asset to accelerate the transition to EV
- SmartSiC™: Greener, Faster, Better. Value Creation & Performance demonstrated
- First customer in Qualification; SmartSiC™ in cars expected by end of CY24
- On track with our roadmap, ready for 1st production in Sept 2023, at our new Fab Bernin 4. Ramp-up in FY25



AUTOMOTIVE
& INDUSTRIAL

THANK YOU